



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

** : Required Field*

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2017-04-21
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	LAURENT TOSI	Representative Title	MDG MD CHAMPION
Representative Phone *	33 442 685 795	Representative Email *	laurent.tosi@st.com
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement


While STMicroelectronics has endeavored to provide information which is accurate and up to date, this document and its contents are provided on a strict 'as is' and 'as available' basis. STMicroelectronics disclaims all warranties, express or implied related to this document and its contents, including but not limited to implied warranties of completeness, truth, accuracy, merchantability, fitness for a particular purpose and non-infringement. ST shall have no responsibility and assumes no liability for any cost, loss or damage of any kind which could arise, directly or indirectly, from the use or inability to use this document and/or its contents.

Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STM32H743VIT6	P01L*450XXXY	A	9998	2017-04-21
	Amount	UoM	Unit type	ST ECOPACK Grade
	681.44	mg	Each	ECOPACK® 2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used or other bulk termination : add in comments	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFP	14x14x1.4	100	L bend	
Comment	Package: 1L LQFP 100 14x14x1.4 1 0086901			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-12th January 2017				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	P01L*450XXY					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	16.439	mg	supplier	die	Silicon (Si)	7440-21-3		15.697	mg	954863	23035
				supplier	metallization	Aluminium (Al)	7429-90-5		0.088	mg	5353	129
				supplier	metallization	Copper (Cu)	7440-50-8		0.276	mg	16789	405
				supplier	passivation	Nickel (Ni)	7440-02-0		0.001	mg	61	1
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.045	mg	2737	66
				supplier	metallization	Titanium (Ti)	7440-32-6		0.008	mg	487	12
				supplier	metallization	Tungsten (W)	7440-33-7		0.001	mg	61	1
				supplier	Passivation	Silicon Oxide	7631-86-9		0.323	mg	19648	474
LEADFRAME (MHT - C194)	Other inorganic materials	141.824	mg	supplier	ALLOY	Copper (Cu)	7440-50-8		138.208	mg	974500	202817
				supplier	ALLOY	Iron (Fe)	7439-89-6		3.404	mg	24000	4995
				supplier	ALLOY	Zinc (Zn)	7440-66-6		0.170	mg	1200	250
				supplier	ALLOY	Metallic Phosphorous (P)	7723-14-0		0.043	mg	300	62
LEADFRAME (MHT - Ag Plating)	Other inorganic materials	1.568	mg	supplier	COATING	Silver(Ag)	7440-22-4		1.568	mg	1000000	2301
DIE ATTACH (Evertech - AP4200)	Other inorganic materials	2.572	mg	supplier	GLUE	Silver(Ag)	7440-22-4		2.006	mg	780000	2944
				supplier	GLUE	Phenolic Resin	9003-35-4		0.039	mg	15000	57
				supplier	GLUE	Ethylene glycol monobutyl ether acetate	112-07-2		0.103	mg	40000	151
				supplier	GLUE	Polymer with oxirane and Phenol	9003-36-5		0.386	mg	150000	566
				supplier	GLUE	1,4-Butanedioldiglycidyl Ether	2425-79-8		0.039	mg	15000	57
BONDING WIRE (Hesung - Au HTS V	Other inorganic materials	1.534	mg	supplier	BONDING WIRE	Gold (Au)	7440-57-5		1.519	mg	990060	2229
				supplier	BONDING WIRE	Calcium (Ca)	7440-70-2		0.000	mg	40	0
				supplier	BONDING WIRE	Palladium (Pd)	7440-05-3		0.015	mg	9900	22
ENCAPSULATION (Sumitomo -G6315H	Other inorganic materials	512.045	mg	supplier	MOLDING COMPOUND	Epoxy Resin A	Trade secret		15.384	mg	30043	22575
				supplier	MOLDING COMPOUND	Epoxy resin B	85954-11-6		20.511	mg	40058	30100
				supplier	MOLDING COMPOUND	Silica Amorphous A (SiO3)	60676-86-0		358.209	mg	699565	525665
				supplier	MOLDING COMPOUND	Silica Amorphous B (SiO3)	7631-86-9		79.482	mg	155225	116638
				supplier	MOLDING COMPOUND	Carbon Black	1333-86-4		2.564	mg	5007	3763
FINISHING (Sytron - Sn100)	Other inorganic materials	5.457	mg	supplier	MOLDING COMPOUND	Phenol Resin	205830-20-2		35.895	mg	70101	52675
				supplier	COATING	Tin (Sn)	7440-31-5		5.457	mg	1000000	8008